Product data sheet

BALVER ZINN®

JEAN-151-SN100C-T3

Rev: 20.10

Date 2021.08.18
Language English
SDS 950632

BALVERZINN.COM

SUMMARY

Pb-free - Halide-free - Premium latest technology No-Clean solder paste

PASTE	JEAN-151-SN100C-T3
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	9

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	8
Pb-free process N2	9
Vapor phase process	7
Shiny joint appearance	9
Cosmetic cleanliness	8
ICCT compatible	N/A
Conformal coating	N/A

Legend	
Especially made for this purpose	9 - 10
Generally qualified for this purpose	7 - 8
Generally usable, but not the best choice	5 - 6
Generally not usable for this purpose	3 - 4
Wrong choice	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

CLASSIFICATION		
DIN-EN-ISO-9454-1: 2016		1122
IPC-J-STD-004-A: 2004		ROL0
IPC-J-STD-005: 1995 (Powder)		T3
Particle size	[µm]	25-45

PROPERTIES			
Flux code			JEAN-151
Alloy Code			SN100C
Alloy composition			Sn99.3Cu0.7NiGe
Liquidus		[°C]	227
Solidus		[°C]	227
Recommended peak temp.		[°C]	238-260
Acid number		[mg KOH/g]	123
Flux		[% w/w]	11.2
Residues			Colorless
Tackiness Malcom TK1	IPC-TM-650 2.4.44	[gf] @ 0h	33

TEST REPORTS			
IPC/ANSI-J-STD-005			Compliant
Certificate of Compliance			Website
Declaration of Conformity 2011/65/EU (RoHS)			Available
Application Note			EN/DE
Copper Mirror	IPC-TM-650 2.3.32		Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate]	Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot]	Pass
Copper Corrosion	IPC-TM-650 2.6.15		Pass
SIR	IPC-TM-650 2.6.3.3		Pass
ECM	IPC-TM-650 2.6.14.1		Pass

PACKAGING AND STORAGE		
Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	12